8-Input Multiplexer with 3-State Outputs

The TTL/MSI SN74LS251 is a high speed 8-Input Digital Multiplexer. It provides, in one package, the ability to select one bit of data from up to eight sources. The LS251 can be used as a universal function generator to generate any logic function of four variables. Both assertion and negation outputs are provided.

- Schottky Process for High Speed
- Multifunction Capability
- On-Chip Select Logic Decoding
- Inverting and Non-Inverting 3-State Outputs
- Input Clamp Diodes Limit High Speed Termination Effects

GUARANTEED OPERATING RANGES

Symbol	Parameter	Min	Тур	Max	Unit
V _{CC}	Supply Voltage	4.75	5.0	5.25	V
T _A	Operating Ambient Temperature Range	0	25	70	°C
I _{OH}	Output Current - High			-2.6	mA
I _{OL}	Output Current – Low			24	mA



ON Semiconductor™

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LOW POWER SCHOTTKY



PLASTIC N SUFFIX CASE 648



SOIC D SUFFIX CASE 751B



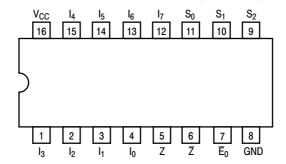
SOEIAJ M SUFFIX CASE 966

ORDERING INFORMATION

Device	Package	Shipping	
SN74LS251N	16 Pin DIP	2000 Units/Box	
SN74LS251D	SOIC-16	38 Units/Rail	
SN74LS251DR2	SOIC-16	2500/Tape & Reel	
SN74LS251M	SOEIAJ-16	See Note 1	
SN74LS251MEL	SOEIAJ-16	See Note 1	

 For ordering information on the EIAJ version of the SOIC package, please contact your local ON Semiconductor representative.

CONNECTION DIAGRAM DIP (TOP VIEW)

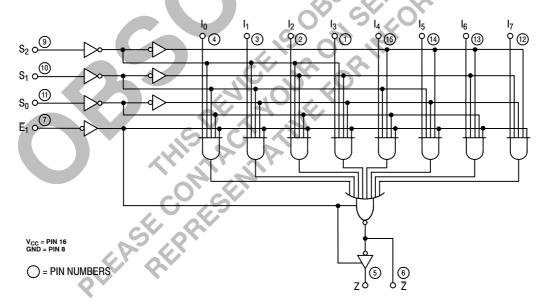


	_	LOADING (Note a)		
PIN NAMES		HIGH	LOW	
S ₀ - S ₂	Select Inputs	0.5 U.L.	0.25 U.L.	
E ₀	Output Enable (Active LOW) Inputs	0.5 U.L.	0.25 U.L.	
l ₀ - l ₇	Multiplexer Inputs	0.5 U.L.	0.25 U.L.	
Z	Multiplexer Output	65 U.L.	15 U.L.	
Z	Complementary Multiplexer Output	65 U.L.	15 U.L.	

NOTES:

a) 1 TTL Unit Load (U.L.) = 40 μ A HIGH/1.6 mA LOW.

LOGIC DIAGRAM



FUNCTIONAL DESCRIPTION

The LS251 is a logical implementation of a single pole, 8-position switch with the switch position controlled by the state of three Select inputs, S₀, S₁, S₂. Both assertion and negation outputs are provided. The Output Enable input (\overline{E}_{O}) is active LOW. When it is activated, the logic function provided at the output is:

$$\begin{split} Z = \overline{E}_O \cdot & [I_O \cdot | \overline{\$}_O \cdot | \overline{\$}_1 \cdot | \overline{\$}_2 | \cdot | I_1 \cdot | \overline{\$}_O \cdot | \overline{\$}_1 \cdot | \overline{\$}_2 + I_2 \cdot | \overline{\$}_O \cdot | \overline{\$}_1 \cdot \\ & \overline{\$}_2 + I_3 \cdot | \overline{\$}_O \cdot | \overline{\$}_1 | \overline{\$}_2 + I_4 \cdot | \overline{\$}_O \cdot | \overline{\$}_1 \cdot | \overline{\$}_2 + I_5 \cdot | \overline{\$}_O \cdot \\ & \overline{\$}_1 \cdot | \overline{\$}_2 + I_6 \cdot | \overline{\$}_O \cdot | \overline{\$}_1 \cdot | \overline{\$}_2 + I_7 \cdot | \overline{\$}_O \cdot | \overline{\$}_1 \cdot | \overline{\$}_2). \end{split}$$

When the Output Enable is HIGH, both outputs are in the high impedance (high Z) state. This feature allows multiplexer expansion by tying the outputs of up to 128 devices together. When the outputs of the 3-state devices are tied together, all but one device must be in the high impedance state to avoid high currents that would exceed the maximum ratings. The Output Enable signals should be designed to ensure there is no overlap in the active LOW portion of the enable voltage.

TRUTH TABLE

E ₀	S ₂	S ₁	S ₀	I ₀	I ₁	l ₂	l ₃	I ₄	l ₅	l ₆	I ₇	Z	Z	
Н	Х	Х	Χ	Х	Х	Χ	Χ	Х	X	X	X	(Z)	(Z)	
L	L	L	L	L	Χ	Χ	Χ	X	Χ	X	X	Н	L	
L	L	L	L	Н	Χ	Χ	Х	X	X	X	X	L	Н	0
L	L	L	Н	Х	L	X	X	X	X	Х	Х	Н	L	.0
L	L	L	H	Х	Н	X	X	X	X	X	X	L	Н	
L	L	Н	L	X	X	L	X	X	X	X	X	H	ŤC.) `
L	L	Н	L	X	X	Н	X	X	X	X	X	L	Н	
L L	L	H H	H H	X	X X	X X	L H	X	X X	X	X	H) H	6
L	H	L	L	x	×	X	Х	Ĺ	X	X X	X	Н)
L	''	L	L	X	X	x	x	Н	X	X	X	P;' .	H	
L	I ::	L	Н	X	X	X	x	X		X X	X	H	Ľ	
L	I н	L	H	X	X	X	X	X	Ħ	X	X		Н	
1	Ιн	н		×	X	Y	Y	×	Y		X	H	L	
L	Н	Н	L	X	X	Χ	X	X	Х	H.	X	L	Н	
L	Н	Н	Н	X	X	Χ	Χ	X	X	Χ	L	Н	L	
L	Н	H	Н	Х	Χ	X	Х	X	X	Х	Н	L	Н	
L = LOW X = Don (Z) = Hiç	/ Voltag	e Level		SPA	A SE				ÇO					

DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

			Limits				
Symbol	Parameter	Min	Тур	Max	Unit	Tes	t Conditions
V _{IH}	Input HIGH Voltage	2.0			V	Guaranteed Inpu All Inputs	t HIGH Voltage for
V _{IL}	Input LOW Voltage			0.8	V	Guaranteed Inpu All Inputs	t LOW Voltage for
V _{IK}	Input Clamp Diode Voltage		-0.65	-1.5	V	V _{CC} = MIN, I _{IN} =	–18 mA
V _{OH}	Output HIGH Voltage	2.4	3.1		V	V_{CC} = MIN, I_{OH} = MAX, V_{IN} = V_{IH} or V_{IL} per Truth Table	
.,	O to HOWAVelland		0.25	0.4	٧	I _{OL} = 12 mA	V _{CC} = V _{CC} MIN,
V_{OL}	Output LOW Voltage		0.35	0.5	V	I _{OL} = 24 mA	V _{IN} = V _{IL} or V _{IH} per Truth Table
I _{OZH}	Output Off Current HIGH			20	μΑ	$V_{CC} = MAX, V_{OU}$	_T = 2.7 V
I _{OZL}	Output Off Current LOW			-20	μА	V _{CC} = MAX, V _{OU}	T = 0.4 V
	land till Cill Command			20	μΑ	V _{CC} = MAX, V _{IN}	= 2.7 V
I _{IH}	Input HIGH Current			0.1	mA	V _{CC} = MAX, V _{IN}	= 7.0 V
I _{IL}	Input LOW Current			-0.4	mA	V _{CC} = MAX, V _{IN}	= 0.4 V
I _{OS}	Short Circuit Current (Note 2)	-30		-130	mA	$V_{CC} = MAX$	4
laa	Power Supply Current			10	mA	$V_{CC} = MAX, V_{E} =$	- 0 V
I _{CC}	Power Supply Current			12	mA	$V_{CC} = MAX, V_{E} =$	- 4.5 V

^{2.} Not more than one output should be shorted at a time, nor for more than 1 second.

AC CHARACTERISTICS (T_A = 25°C, V_{CC} = 5.0 V)

			Limits	5	19	716	
Symbol	Parameter	Min	Тур	Max	Unit	Test	Conditions
t _{PLH} t _{PHL}	Propagation Delay, Select to Z Output	1	20 21	33 33	ns	Figure 1	
t _{PLH} t _{PHL}	Propagation Delay, Select to Z Output	0%	29 28	45 45	ns	Figure 2	
t _{PLH} t _{PHL}	Propagation Delay, Data to Z Output	X PC	10 9.0	15 15	ns	Figure 1	C _L = 15 pF,
t _{PLH} t _{PHL}	Propagation Delay, Data to Z Output		17 18	28 28	ns	Figures 2	$R_L = 2.0 \text{ k}\Omega$
t _{PZH} t _{PZL}	Output Enable Time to Z Output		17 24	27 40	ns	Figures 4, 5	
t _{PZH} t _{PZL}	Output Enable Time to Z Output		30 26	45 40	ns	Figures 3, 5	
t _{PHZ} t _{PLZ}	Output Disable Time to Z Output		37 15	55 25	ns	Figures 3, 5	C _L = 5.0 pF,
t _{PHZ} t _{PLZ}	Output Disable Time to Z Output		30 15	45 25	ns	Figures 4, 5	$R_L = 667 \text{ k}\Omega$

3-STATE AC WAVEFORMS

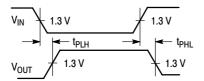


Figure 1.

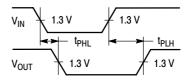


Figure 2.

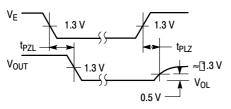
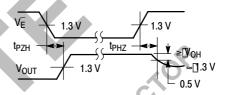
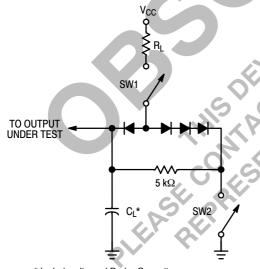


Figure 3.

0.5 V





^{*} Includes Jig and Probe Capacitance.

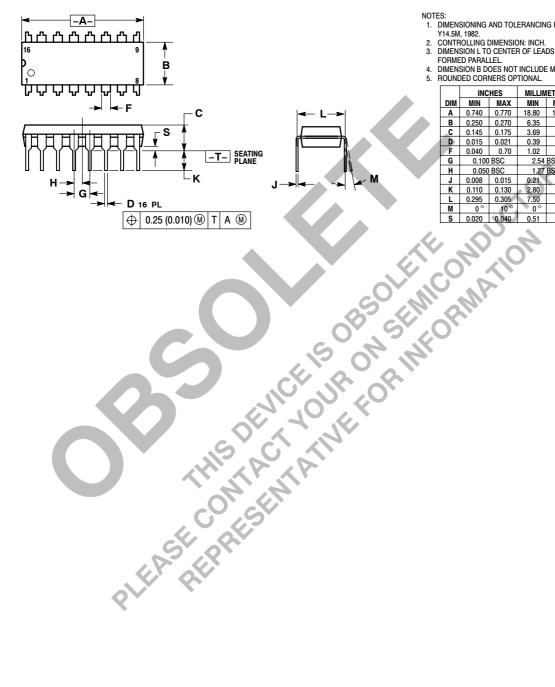
SWITCH POSITIONS

		41 OF	
AC LOAD CIRCUIT	SEMICO PA	MA	
ILIS ON	a INFO	/ITCH POSITIO	NS
Mo Ohio	SYMBOL	SW1	SW2
570 CX	t _{PZH}	Open	Closed
1 10	t _{PZL}	Closed	Open
	t _{PLZ}	Closed	Closed
	·		

Figure 5.

PACKAGE DIMENSIONS

N SUFFIX PLASTIC PACKAGE CASE 648-08 ISSUE R



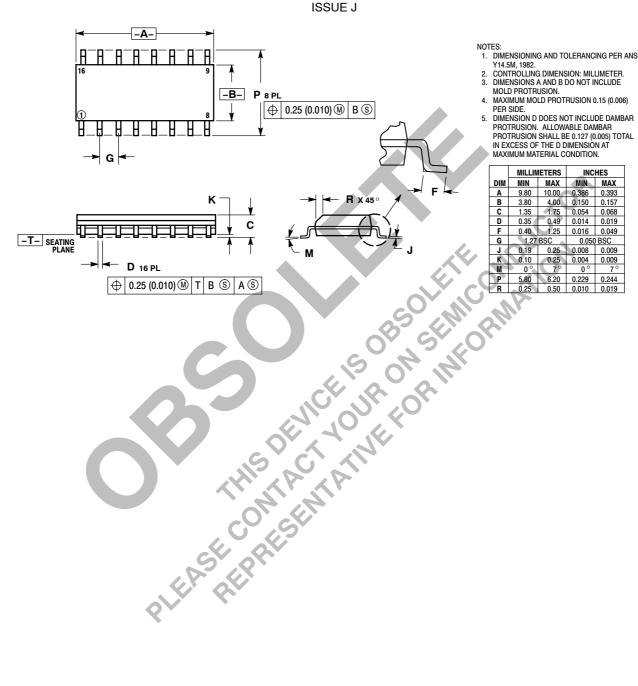
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
 DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

		INC	HES	MILLIMETERS				
	DIM	MIN	MAX	MIN	MAX			
	Α	0.740	0.770	18.80	19.55			
	В	0.250	0.270	6.35	6.85			
	Ç	0.145	0.175	3.69	4.44			
d	Ď	0.015	0.021	0.39	0.53			
ı	F	0.040	0.70	1.02	1.77			
4	G	0.100	BSC	2.54	BSC			
	Н	0.050	BSC	1.27 BSC				
	J	0.008	0.015	0.21	0.38			
	K	0.110	0.130	2.80	3.30			
	L	0.295	0.305	7.50	7.74			
	M	0°	10°	0 °	10 °			
	9	0.020	0.040	0.51	1 01			

PACKAGE DIMENSIONS

D SUFFIX PLASTIC SOIC PACKAGE CASE 751B-05



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

- Y14.5M, 1982.

 CONTROLLING DIMENSION: MILLIMETER.

 DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.

 MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

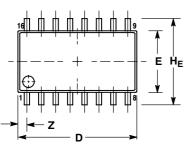
 DIMENSION D DOES NOT INCLUDE DAMBAR
- PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION. SHALL BE 0.127 (0.005) TOTAL
 IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

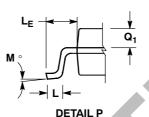
	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	9.80	10.00	0.386	0.393
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050 BSC	
J∢	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0 °	7°
P	5.80	6.20	0.229	0.244
P	0.05	0.50	0.010	0.010

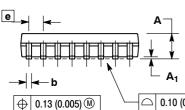
PACKAGE DIMENSIONS

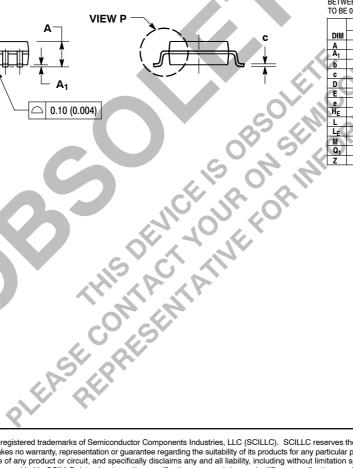
M SUFFIX

SOEIAJ PACKAGE CASE 966-01 **ISSUE O**









NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS D AND E DO NOT INCLUDE MOLD 3. FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE, MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE
- TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
 THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH
 DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	-	2.05	-	0.081	
A ₁	0.05	0.20	0.002	0.008	
b	0.35	0.50	0.014	0.020	
C	0.18	0.27	0.007	0.011	
D	9.90	10.50	0.390	0.413	
E	5.10	5.45	0.201	0.215	
e	1.27	BSC	0.050 BSC		
HE	7.40	8.20	0.291	0.323	
L	0.50	0.85	0.020	0.033	
LE	1.10	1.50	0.043	0.059	
M	0 °	10°	0°	10 °	
Q_1	0.70	0.90	0.028	0.035	
Z		0.78		0.031	

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